

IN THE CLAIMS:

Claims 5, 6, and 13-52 were previously cancelled. Claim 7 has been amended herein.

All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Previously presented) A semiconductor device package, comprising:
a semiconductor device including at least one bond pad on an active surface thereof and at least one recess in a peripheral edge thereof;
at least one outer connector corresponding to the at least one bond pad, the at least one outer connector positioned at least partially within the at least one recess and having a height that extends substantially along a height of the peripheral edge, the at least one outer connector comprising:
opposite surfaces exposed at the active surface and a back side of the semiconductor device; and
a recess extending substantially from one of the opposite surfaces to another of the opposite surfaces; and
at least one conductive trace extending between the at least one bond pad and the at least one outer connector.

2. (Original) The semiconductor device package of claim 1, further comprising:
an insulative layer positioned beneath at least the at least one conductive trace.

3. (Original) The semiconductor device package of claim 1, further comprising:
an insulative layer positioned over at least the at least one conductive trace and the at least one bond pad.

4. (Original) The semiconductor device package of claim 1, further comprising:
a back side insulative layer substantially covering a back side of the semiconductor device.

5. (Cancelled)

6. (Cancelled)

7. (Currently amended) The semiconductor device package of claim 1, wherein the recess of the at least one outer connector has a semicylindrical shape.

8. (Original) The semiconductor device package of claim 1, comprising a plurality of outer connectors.

9. (Original) The semiconductor device package of claim 8, comprising a plurality of conductive traces that corresponds to at least some of the plurality of outer connectors.

10. (Original) The semiconductor device package of claim 9, wherein each of the plurality of conductive traces establishes electrical communication between a bond pad of the semiconductor device and a corresponding outer connector of the plurality of outer connectors.

11. (Original) The semiconductor device package of claim 8, wherein each of the plurality of outer connectors is positioned on a single peripheral edge of the semiconductor device.

12. (Original) The semiconductor device package of claim 8, wherein outer connectors of the plurality of outer connectors are positioned adjacent to at least two peripheral edges of the semiconductor device.

13.-52. (Cancelled)